

ABSTRACT

An intermediate board comprising: an intermediate board body having first and second faces wherein a semiconductor device is to be mounted on at least one of said first and second faces, said semiconductor device having a coefficient of thermal expansion that is equal to or larger than 2.0 ppm/ $^{\circ}$ C and smaller than 5.0 ppm/ $^{\circ}$ C, and having surface mount terminals, said intermediate board body having a plurality of through holes through which said first and second faces communicate with each other, said intermediate board body containing an inorganic insulating material; and a plurality of conductor columns filling said through holes and containing a conductive metal, said conductor columns being to be connected with said surface mount terminals.